NBSG53A

2.5V/3.3V SiGe Selectable Differential Clock and Data D Flip-Flop/Clock Divider with Reset and OLS*

The NBSG53A is a multi-function differential D flip-flop (DFF) or fixed divide by two (DIV/2) clock generator. This is a part of the GigaComm™ family of high performance Silicon Germanium products. A strappable control pin is provided to select between the two functions. The device is housed in a low profile 4x4 mm 16-pin Flip-Chip BGA (FCBGA) or a 3x3 mm 16 pin QFN package.

The NBSG53A is a device with data, clock, OLS, reset, and select inputs. Differential inputs incorporate internal 50 Ω termination resistors and accept NECL (Negative ECL), PECL (Positive ECL), LVCMOS/LVTTL, CML, or LVDS. The OLS input is used to program the peak-to-peak output amplitude between 0 and 800 mV in five discrete steps. The RESET and SELECT inputs are single-ended and can be driven with either LVECL or LVCMOS/LVTTL input levels.

Data is transferred to the outputs on the positive edge of the clock. The differential clock inputs of the NBSG53A allow the device to also be used as a negative edge triggered device.

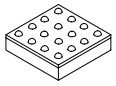
- Maximum Input Clock Frequency (DFF) > 8 GHz Typical (See Figures 4, 6, 8, 10, and 11)
- Maximum Input Clock Frequency (DIV/2) > 10 GHz Typical (See Figures 5, 7, 9, 10, and 11)
- 210 ps Typical Propagation Delay (OLS = FLOAT)
- 45 ps Typical Rise and Fall Times (OLS = FLOAT)
- DIV/2 Mode (Active with Select Low)
- DFF Mode (Active with Select High)
- Selectable Swing PECL Output with Operating Range: V_{CC} = 2.375 V to 3.465 V with V_{EE} = 0 V
- Selectable Swing NECL Output with NECL Inputs with Operating Range: V_{CC} = 0 V with V_{EE} = -2.375 V to -3.465 V
- Selectable Output Level (0 V, 200 mV, 400 mV, 600 mV, or 800 mV Peak-to-Peak Output)
- 50 Ω Internal Input Termination Resistors on all Differential Inputs

*Output Level Select

ON Semiconductor®

http://onsemi.com

MARKING DIAGRAM**



FCBGA-16
BA SUFFIX
CASE 489

QFN-16
MN SUFFIX
CASE 485G

A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week

**For further details, refer to Application Note AND8002/D

ORDERING INFORMATION

Device	Package	Shipping
NBSG53ABA	4x4 mm FCBGA-16	100 Units/Tray
NBSG53ABAR2	4x4 mm FCBGA-16	500/Tape & Reel
NBSG53MN	3x3 mm QFN-16	123 Units/Rail
NBSG53MNR2	3x3 mm QFN-16	3000/Tape & Reel

Board	Description
NBSG53ABAEVB	NBSG53ABA Evaluation Board

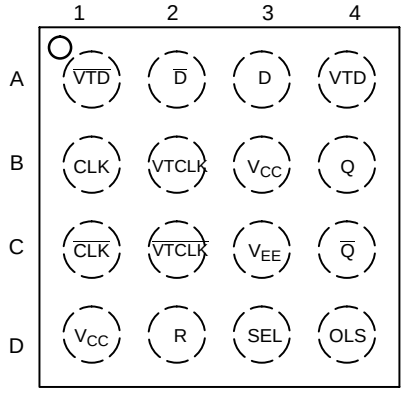


Figure 1. BGA-16 Pinout (Top View)

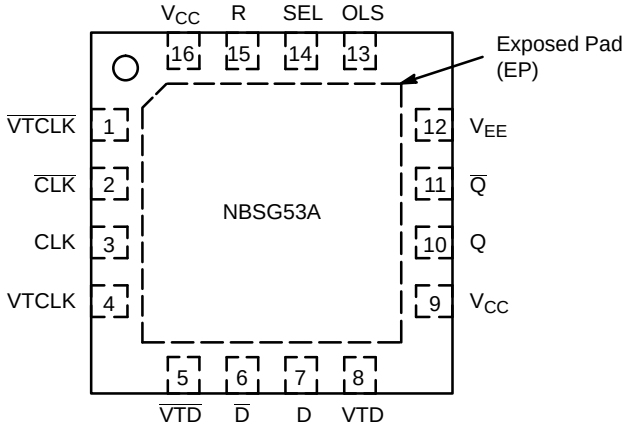


Figure 2. QFN-16 Pinout (Top View)

Table 1. Pin Description

Pin		Name	I/O	Description
BGA	QFN			
C2	1	$\overline{VTCLK}$	-	Internal 50 Ω Termination Pin. See Table 4.
C1	2	$\overline{CLK}$	ECL, CML, LVCMOS, LVDS, LVTTL Input	Inverted Differential Input.
B1	3	CLK	ECL, CML, LVCMOS, LVDS, LVTTL Input	Noninverted Differential Input.
B2	4	VTCLK	-	Internal 50 Ω Termination Pin. See Table 4.
A1	5	$\overline{VTD}$	-	Internal 50 Ω termination pin. See Table 4.
A2	6	$\overline{D}$	ECL, CML, LVCMOS, LVDS, LVTTL Input	Inverted Differential Input.
A3	7	D	ECL, CML, LVCMOS, LVDS, LVTTL Input	Noninverted Differential Input.
A4	8	VTD	-	Internal 50 Ω Termination Pin. See Table 4.
D1,B3	9,16	V_{CC}	-	Positive Supply Voltage
B4	10	Q	RSECL Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to $V_{TT} = V_{CC}$ - 2 V.
C4	11	$\overline{Q}$	RSECL Output	Noninverted Differential Output. Typically Terminated with 50 Ω Resistor to $V_{TT} = V_{CC}$ - 2 V.
C3	12	V_{EE}	-	Negative Supply Voltage
D4	13	OLS*	Input	Input Pin for the Output Level Select (OLS). See Table 2.
D3	14	SEL	LVECL, LVCMOS, LVTTL Input	Select Logic Input. Internal 75 kΩ to V_{EE}.
D2	15	R	LVECL, LVCMOS, LVTTL Input	Reset D Flip-Flop. Internal 75 kΩ to V_{EE}.
N/A	-	EP		Exposed Pad. (Note 1)

1. All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation. The thermally exposed pad (EP) on package bottom (see case drawing) must be attached to a heat-sinking conduit.
2. In the differential configuration when the input termination pins (VTD, $\overline{VTD}$, VTCLK, $\overline{VTCLK}$) are connected to a common termination voltage, and if no signal is applied then the device will be susceptible to self-oscillation.
3. When an output level of 400 mV is desired and V_{CC} - V_{EE} > 3.0 V, 2KΩ resistor should be connected from OLS pin to V_{EE}.

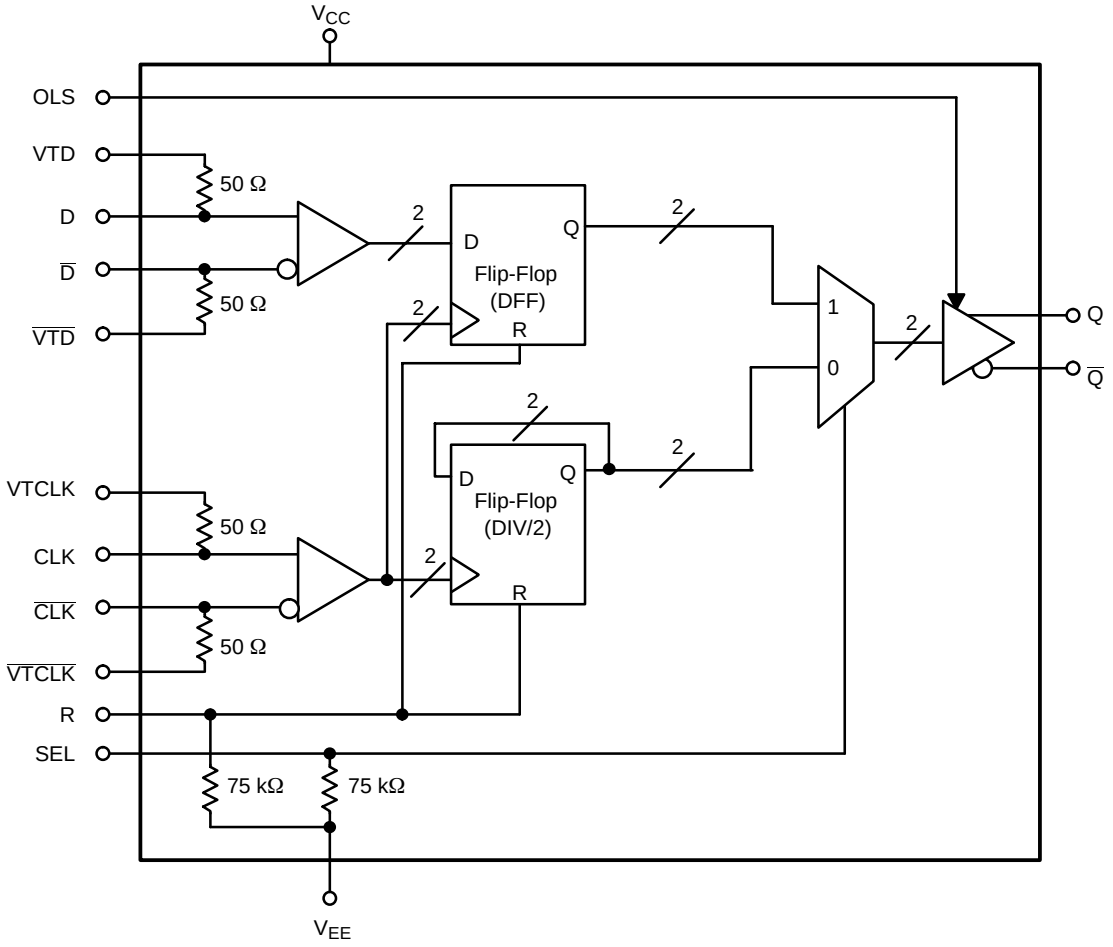


Figure 3. Simplified Logic Diagram

Table 2. OUTPUT LEVEL SELECT (OLS)

OLS	Q/$\overline{Q}$ VPP	OLS Sensitivity
V_{CC}	800 mV	OLS - 75 mV
V_{CC} - 0.4 V	200 mV	OLS ± 150 mV
V_{CC} - 0.8 V	600 mV	OLS ± 100 mV
V_{CC} - 1.2 V	0	OLS ± 75 mV
V_{EE} (Note 4)	400 mV	OLS + 100 mV
Float	600 mV	N/A

4. When an output level of 400 mV is desired and V_{CC} - V_{EE} > 3.0 V, 2.0 kΩ resistor should be connected from OLS to V_{EE}.

Table 3. TRUTH TABLE

R	SEL	D	CLK	Q	Function
H	x	x	x	L	Reset
L	H	L	Z	L	DFF
L	H	H	Z	H	DFF
L	L	x	Z	$\overline{Q}$	DIV/2

Z = LOW to HIGH Transition

Table 4. INTERFACING OPTIONS

INTERFACING OPTIONS	CONNECTIONS
CML	Connect VTCLK, VTD and $\overline{VTCLK}$, $\overline{VTD}$ to V_{CC}
LVDS	Connect VTCLK, VTD and $\overline{VTCLK}$, $\overline{VTD}$ Together
AC-COUPLED	Bias VTCLK, VTD and $\overline{VTCLK}$, $\overline{VTD}$ Inputs within Common Mode Range (V_{IHCMR})
RSECL, PECL, NECL	Standard ECL Termination Techniques
LVTTL, LVCMOS	An External Voltage (V_{THR}) should be Applied to the Unused Complementary Differential Input. Nominal V_{THR} is 1.5 V for LVTTL and V_{CC}/2 for LVCMOS Inputs. This Voltage must be within the V_{THR} Specification.

Table 5. ATTRIBUTES

Characteristics		Value
Positive Operating Voltage Range for V_{CC} (V_{EE} = 0 V)		2.375 V to 3.465 V
Negative Operating Voltage Range for V_{EE} (V_{CC} = 0 V)		-2.375 V to -3.465 V
Internal Input Pulldown Resistor (R, SEL)		75 kΩ
ESD Protection	Human Body Model Machine Model Charged Device Model	> 1.5 kV > 50 V > 4 kV
Moisture Sensitivity (Note 5)	16-FCBGA 16-QFN	Level 3 Level 1
Flammability Rating		UL 94 V-0 @ 0.125 in
Oxygen Index		28 to 34
Transistor Count		482
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

5. For additional information, refer to Application Note AND8003/D.

Table 6. MAXIMUM RATINGS (Note 6)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V_{CC}	Positive Power Supply	V_{EE} = 0 V		3.6	V
V_{EE}	Negative Power Supply	V_{CC} = 0 V		-3.6	V
V_I	Positive Input Negative Input	V_{EE} = 0 V V_{CC} = 0 V	$V_I \le V_{CC}$ $V_I \ge V_{EE}$	3.6 -3.6	V V
V_{INPP}	Differential Input Voltage $\lvert D - \overline{D} \rvert$	$V_{CC} - V_{EE} \ge$ 2.8 V $V_{CC} - V_{EE} <$ 2.8 V		2.8 $\lvert V_{CC} - V_{EE} \rvert$	V V
I_{IN}	Input Current Through R_T (50 Ω Resistor)	Static Surge		45 80	mA mA
I_{OUT}	Output Current	Continuous Surge		25 50	mA mA
T_A	Operating Temperature Range	16 FCBGA 16 QFN		-40 to +70 -40 to +85	°C
T_{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient) (Note 7)	0 LFPM 500 LFPM 0 LFPM 500 LFPM	16 FCBGA 16 FCBGA 16 QFN 16 QFN	108 86 41.6 35.2	°C/W °C/W °C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	2S2P (Note 7) 2S2P (Note 8)	16 FCBGA 16 QFN	5.0 4.0	°C/W °C/W
T_{sol}	Wave Solder	< 15 Seconds		225	°C

6. Maximum Ratings are those values beyond which device damage may occur.
7. JEDEC standard 51-6, multilayer board - 2S2P (2 signal, 2 power).
8. JEDEC standard multilayer board - 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 7. DC CHARACTERISTICS, INPUT WITH PECL OUTPUT V_{CC} = 2.5 V; V_{EE} = 0 V (Note 9)

Symbol	Characteristic	-40 °C			25°C			70°C(BGA)/85°C(QFN)**			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Negative Power Supply Current	33	45	57	33	45	57	33	45	57	mA
V_{OH}	Output HIGH Voltage (Note 10)	1460	1510	1560	1490	1540	1590	1515	1565	1615	mV
V_{OL}	Output LOW Voltage (Note 10)										mV
	($OLS = V_{CC}$)	555	705	855	595	745	895	625	775	925	
	($OLS = V_{CC}$ - 0.4 V)	1235	1295	1355	1270	1330	1390	1295	1355	1415	
	($OLS = V_{CC}$ - 0.8 V, OLS = FLOAT)	775	895	1015	810	930	1050	840	960	1080	
	($OLS = V_{CC}$ - 1.2 V)	1455	1505	1555	1490	1540	1590	1510	1560	1610	
	($OLS = V_{EE}$)	1005	1095	1185	1040	1130	1220	1065	1155	1245	
V_{OUTPP}	Output Voltage Amplitude										mV
	($OLS = V_{CC}$)	715	805		705	795		700	790		
	($OLS = V_{CC}$ - 0.4 V)	125	215		120	210		120	210		
	($OLS = V_{CC}$ - 0.8 V, OLS = FLOAT)	525	615		520	610		515	605		
	($OLS = V_{CC}$ - 1.2 V)	0	5		0	0		0	5		
	($OLS = V_{EE}$)	325	415		320	410		320	410		
V_{IH}	Input HIGH Voltage (Single-Ended) (Notes 12 and 14) CLK, $\overline{CLK}$, D, $\overline{D}$	V_{EE} + 1275	V_{CC} - 1000*	V_{CC}	V_{EE} + 1275	V_{CC} - 1000*	V_{CC}	V_{EE} + 1275	V_{CC}- 1000*	V_{CC}	mV
V_{IL}	Input LOW Voltage (Single-Ended) (Notes 13 and 14) CLK, $\overline{CLK}$, D, $\overline{D}$	V_{EE}	V_{CC}- 1400*	V_{IH}- 150	V_{EE}	V_{CC}- 1400*	V_{IH}- 150	V_{EE}	V_{CC}- 1400*	V_{IH}- 150	mV
V_{IH}	Input High Voltage (Single-Ended) R, SEL	1290		V_{CC}	1355		V_{CC}	1415		V_{CC}	mV
V_{IL}	Input Low Voltage (Single-Ended) R, SEL	V_{EE}		890	V_{EE}		955	V_{EE}		1015	mV
V_{THR}	Input Threshold Voltage (Single-Ended) (Note 14)	V_{EE}+ 1125		V_{CC}- 75	V_{EE}+ 1125		V_{CC}- 75	V_{EE}+ 1125		V_{CC}- 75	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 11)	1.2		2.5	1.2		2.5	1.2		2.5	V
R_{TIN}	Internal Input Termination Resistor	45	50	55	45	50	55	45	50	55	Ω
I_{IH}	Input HIGH Current (@V_{IH}) R, SEL		35	100		35	100		35	100	μA
	CLK, $\overline{CLK}$, D, $\overline{D}$		5	50		5	50		5	50	
I_{IL}	Input LOW Current (@V_{IL}) R, SEL		20	100		20	100		20	100	μA
	CLK, $\overline{CLK}$, D, $\overline{D}$		5	50		5	50		5	50	

NOTE: GigaComm circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

9. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.125 V to -0.965 V.
10. All outputs loaded with 50 Ω to V_{CC} - 2.0 V.
11. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.
12. V_{IH} cannot exceed V_{CC}. $|V_{IH} - V_{THR}| < 2600$ mV.
13. V_{IL} always $\geq V_{EE}$. $|V_{IL} - V_{THR}| < 2600$ mV.
14. V_{THR} is the voltage applied to one input when running in single-ended mode.

*Typicals used for testing purposes.

**The device packaged in FCBGA-16 have maximum ambient temperature specification of 70°C and devices packaged in QFN-16 have maximum ambient temperature specification of 85°C.

Table 8. DC CHARACTERISTICS, INPUT WITH PECL OUTPUT V_{CC} = 3.3 V; V_{EE} = 0 V (Note 15)

Symbol	Characteristic	-40 °C			25°C			70°C(BGA)/85°C(QFN)***			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Negative Power Supply Current	35	47	59	35	47	59	35	47	59	mA
V_{OH}	Output HIGH Voltage (Note 16)	2260	2310	2360	2290	2340	2390	2315	2365	2415	mV
V_{OL}	Output LOW Voltage (Note 16)										mV
	(OLS = V_{CC})	1320	1470	1620	1360	1510	1660	1390	1540	1690	
	(OLS = V_{CC} - 0.4 V)	2030	2090	2150	2065	2125	2185	2090	2150	2210	
	(OLS = V_{CC} - 0.8 V, OLS = FLOAT)	1550	1670	1790	1585	1705	1825	1615	1735	1855	
	(OLS = V_{CC} - 1.2 V)	2260	2310	2360	2290	2340	2390	2315	2365	2415	
	**(OLS = V_{EE})	1785	1875	1965	1820	1910	2000	1850	1940	2030	
V_{OUTPP}	Output Amplitude Voltage										mV
	(OLS = V_{CC})	750	840		740	830		735	825		
	(OLS = V_{CC} - 0.4 V)	130	220		125	215		125	215		
	(OLS = V_{CC} - 0.8 V, OLS = FLOAT)	550	640		545	635		540	630		
	(OLS = V_{CC} - 1.2 V)	0	0		0	0		0	0		
	**(OLS = V_{EE})	345	435		340	430		335	425		
V_{IH}	Input HIGH Voltage (Single-Ended) (Notes 18 and 20) CLK, $\overline{CLK}$, D, $\overline{D}$	V_{EE} + 1275	V_{CC} - 1000*	V_{CC}	V_{EE} + 1275	V_{CC} - 1000*	V_{CC}	V_{EE} + 1275	V_{CC} - 1000*	V_{CC}	mV
V_{IL}	Input LOW Voltage (Single-Ended) (Notes 19 and 20) CLK, $\overline{CLK}$, D, $\overline{D}$	V_{IH}- 2600	V_{CC}- 1400*	V_{IH}- 150	V_{IH}- 2600	V_{CC}- 1400*	V_{IH}- 150	V_{IH}- 2600	V_{CC}- 1400*	V_{IH}- 150	mV
V_{IH}	Input High Voltage (Single-Ended) R, SEL	2090		V_{CC}	2155		V_{CC}	2215		V_{CC}	mV
V_{IL}	Input Low Voltage (Single-Ended) R, SEL	V_{EE}		1690	V_{EE}		1755	V_{EE}		1815	mV
V_{THR}	Input Threshold Voltage (Single-Ended) (Note 20)	V_{EE}+ 1125		V_{CC}- 75	V_{EE}+ 1125		V_{CC}- 75	V_{EE}+ 1125		V_{CC}- 75	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 17)	1.2		3.3	1.2		3.3	1.2		3.3	V
R_{TIN}	Internal Input Termination Resistor	45	50	55	45	50	55	45	50	55	Ω
I_{IH}	Input HIGH Current (@V_{IH}) R, SEL		35	100		35	100		35	100	μA
	CLK, $\overline{CLK}$, D, $\overline{D}$		5	50		5	50		5	50	
I_{IL}	Input LOW Current (@V_{IL}) R, SEL		20	100		20	100		20	100	μA
	CLK, $\overline{CLK}$, D, $\overline{D}$		5	50		5	50		5	50	

NOTE: GigaComm Circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

15. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.925 V to -0.165 V.
16. All outputs loaded with 50 Ω to V_{CC} - 2.0 V.
17. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.
18. V_{IH} cannot exceed V_{CC}. $|V_{IH} - V_{THR}| < 2600$ mV.
19. V_{IL} always $\geq V_{EE}$. $|V_{IL} - V_{THR}| < 2600$ mV.
20. V_{THR} is the voltage applied to one input when running in single-ended mode.

*Typicals used for testing purposes.

**When an output level of 400 mV is desired and $V_{CC} - V_{EE} > 3.0$ V, a 2 kΩ resistor should be connected from OLS to V_{EE}.

***The device packaged in FCBGA-16 have maximum ambient temperature specification of 70°C and devices packaged in QFN-16 have maximum ambient temperature specification of 85°C.

Table 9. DC CHARACTERISTICS, NECL INPUT WITH NECL OUTPUT
V_{CC} = 0 V; V_{EE} = -3.465 V to -2.375 V (Note 21)

		-40 °C			25°C			70°C(BGA)/85°C(QFN)***			
Symbol	**Characteristic**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
I_{EE}	Negative Power Supply Current	35	47	59	35	47	59	35	47	59	mA
V_{OH}	Output HIGH Voltage (Note 22)	-1040	-990	-940	-1010	-960	-910	-985	-935	-885	mV
V_{OL}	Output LOW Voltage (Note 22)										mV
	-3.465 V ≤ V_{EE} ≤ -3.0 V										
	(V_{OLS} = V_{CC})	-1980	-1830	-1680	-1940	-1790	-1640	-1910	-1760	-1610	
	(V_{OLS} = V_{CC} - 0.4 V)	-1270	-1210	-1150	-1235	-1175	-1115	-1210	-1150	-1090	
	(V_{OLS} = V_{CC} - 0.8 V, OLS =FLOAT)	-1750	-1630	-1510	-1715	-1595	-1475	-1685	-1565	-1445	
	(V_{OLS} = V_{CC} - 1.2 V)	-1040	-990	-940	-1010	-960	-910	-985	-935	-885	
	**(V_{OLS} = V_{EE})	-1515	-1425	-1335	-1480	-1390	-1300	-1450	-1360	-1270	
	-3.0 V < V_{EE} ≤ -2.375 V										
	(V_{OLS} = V_{CC})	-1945	-1795	-1645	-1905	-1755	-1605	-1875	-1725	-1575	
	(V_{OLS} = V_{CC} - 0.4 V)	-1265	-1205	-1145	-1230	-1170	-1110	-1205	-1145	-1085	
	(V_{OLS} = V_{CC} - 0.8 V, OLS =FLOAT)	-1725	-1605	-1485	-1690	-1570	-1450	-1660	-1540	-1420	
	(V_{OLS} = V_{CC} - 1.2 V)	-1045	-995	-945	-1010	-960	-910	-990	-940	-890	
	(V_{OLS} = V_{EE})	-1495	-1405	-1315	-1460	-1370	-1280	-1435	-1345	-1255	
V_{OUTPP}	Output Voltage Amplitude										mV
	-3.465 V ≤ V_{EE} ≤ -3.0 V										
	(V_{OLS} = V_{CC})	750	840		740	830		735	825		
	(V_{OLS} = V_{CC} - 0.4 V)	130	220		125	215		125	215		
	(V_{OLS} = V_{CC} - 0.8 V, OLS = FLOAT)	550	640		545	635		540	630		
	(V_{OLS} = V_{CC} - 1.2 V)	0	0		0	0		0	0		
	**(V_{OLS} = V_{EE})	345	435		340	430		335	425		
	-3.0 V < V_{EE} ≤ -2.375 V										
	(V_{OLS} = V_{CC})	715	805		705	795		700	790		
	(V_{OLS} = V_{CC} - 0.4 V)	125	215		120	210		120	210		
	(V_{OLS} = V_{CC} - 0.8 V, OLS =FLOAT)	525	615		520	610		515	605		
	(V_{OLS} = V_{CC} - 1.2 V)	0	5		0	0		0	5		
	(V_{OLS} = V_{EE})	325	415		320	410		320	410		
V_{IH}	Input HIGH Voltage (Single- Ended) (Notes 24 and 26) CLK, $\overline{CLK}$, D, $\overline{D}$	V_{EE} + 1275	V_{CC} - 1000*	V_{CC}	V_{EE} + 1275	V_{CC} - 1000*	V_{CC}	V_{EE} + 1275	V_{CC} - 1000*	V_{CC}	mV
V_{IL}	Input LOW Voltage (Single- Ended) (Notes 25 and 26) CLK, $\overline{CLK}$, D, $\overline{D}$	V_{IH}- 2600	V_{CC}- 1400*	V_{IH}- 150	V_{IH}- 2600	V_{CC}- 1400*	V_{IH}- 150	V_{IH}- 2600	V_{CC}- 1400*	V_{IH}- 150	mV
V_{IH}	Input High Voltage (Single-Ended) R, SEL	-1210		V_{CC}	-1145		V_{CC}	-1085		V_{CC}	mV
V_{IL}	Input Low Voltage (Single-Ended) R, SEL	V_{EE}		-1610	V_{EE}		-1545	V_{EE}		-1485	mV
V_{THR}	Input Threshold Voltage (Single-Ended) (Note 26)	V_{EE}+ 1125		V_{CC}- 75	V_{EE}+ 1125		V_{CC}- 75	V_{EE}+ 1125		V_{CC}- 75	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 23)	V_{EE} + 1.2		0.0	V_{EE} + 1.2		0.0	V_{EE} + 1.2		0.0	V

NOTE: GigaComm circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

21. Input and output parameters vary 1:1 with V_{CC}.
22. All outputs loaded with 50 Ω to V_{CC} - 2.0 V.
23. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.
24. V_{IH} cannot exceed V_{CC}. $|V_{IH} - V_{THR}| < 2600$ mV.
25. V_{IL} always ≥ V_{EE}. $|V_{IL} - V_{THR}| < 2600$ mV.
26. V_{THR} is the voltage applied to one input when running in single-ended mode.

*Typicals used for testing purposes.
**When an output level of 400 mV is desired and V_{CC} - V_{EE} > 3.0 V, a 2 kΩ resistor should be connected from OLS to V_{EE}.
***The device packaged in FCBGA-16 have maximum ambient temperature specification of 70°C and devices packaged in QFN-16 have maximum ambient temperature specification of 85°C.

Table 9. DC CHARACTERISTICS, NECL INPUT WITH NECL OUTPUT
V_{CC} = 0 V; V_{EE} = -3.465 V to -2.375 V (Note 21) (continued)

		-40 °C			25°C			70°C(BGA)/85°C(QFN)***			
Symbol	**Characteristic**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
R_{TIN}	Internal Input Termination Resistor	45	50	55	45	50	55	45	50	55	Ω
I_{IH}	Input HIGH Current (@V_{IH})										μA
	R, SEL		35	100		35	100		35	100	
	CLK, $\overline{CLK}$, D, $\overline{D}$		5	50		5	50		5	50	
I_{IL}	Input LOW Current (@V_{IL})										μA
	R, SEL		20	100		20	100		20	100	
	CLK, $\overline{CLK}$, D, $\overline{D}$		5	50		5	50		5	50	
I_{OLS}	OLS Input Current (See Figure 12)		300	900		300	900		300	900	μA
	($OLS = V_{CC}$)		100	300		100	300		100	300	
	($OLS = V_{CC}$ - 0.4 V)		5	100		5	100		5	100	
	($OLS = V_{CC}$ - 0.8 V, OLS = FLOAT)	-300	-100		-300	-100		-300	-100		
	($OLS = V_{CC}$ - 1.2 V)	-1500	-600		-1500	-600		-1500	-600		
	-3.465 V ≤ V_{EE} ≤ -3.0 V *($OLS = V_{EE}$)	-1000	-400		-1000	-400		-1000	-400		
	-3.0 V < V_{EE} ≤ -2.375 V ($OLS = V_{EE}$)										

NOTE: GigaComm circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

21. Input and output parameters vary 1:1 with V_{CC}.
22. All outputs loaded with 50 Ω to V_{CC} - 2.0 V.
23. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.
24. V_{IH} cannot exceed V_{CC}. $|V_{IH} - V_{THR}| < 2600$ mV.
25. V_{IL} always ≥ V_{EE}. $|V_{IL} - V_{THR}| < 2600$ mV.
26. V_{THR} is the voltage applied to one input when running in single-ended mode.

*Typicals used for testing purposes.
**When an output level of 400 mV is desired and $V_{CC} - V_{EE} > 3.0$ V, a 2 kΩ resistor should be connected from OLS to V_{EE}.
***The device packaged in FCBGA-16 have maximum ambient temperature specification of 70°C and devices packaged in QFN-16 have maximum ambient temperature specification of 85°C.

Table 10. AC CHARACTERISTICS for FCBGA-16

V_{CC} = 0 V; V_{EE} = -3.465 V to -2.375 V or V_{CC} = 2.375 V to 3.465 V; V_{EE} = 0 V

		-40 °C			25°C			70°C			
Symbol	**Characteristic**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
f_{max}	Maximum Frequency (See Figures 4, 6, 8, 10, and 11) DFF (See Figures 5, 7, 9, 10, and 11) (Note 27) DIV/2		8 10			8 10			8 10		GHz
t_{PLH}, t_{PHL}	Propagation Delay to Output Differential CLK→Q, $\overline{Q}$										ps
	(OLS = V_{CC})	160	210	260	160	215	270	165	220	275	
	(OLS = V_{CC} - 0.4 V)	150	200	250	155	205	255	160	210	260	
	(OLS = V_{CC} - 0.8 V, OLS = FLOAT)	155	205	255	160	210	260	160	215	270	
	**(OLS = V_{EE})	155	205	255	160	210	260	160	215	270	
	SEL→Q, $\overline{Q}$										
	(OLS = V_{CC})	165	220	275	170	225	280	170	225	280	
	(OLS = V_{CC} - 0.4 V)	160	210	260	160	210	260	160	210	260	
	(OLS = V_{CC} - 0.8 V, OLS = FLOAT)	160	215	270	165	220	275	165	220	275	
	**(OLS = V_{EE})	160	210	260	160	215	270	165	220	275	
	R→Q, $\overline{Q}$										
	(OLS = V_{CC}) DIV/2	220	295	370	225	300	375	225	300	375	
	(OLS = V_{CC}) DFF	200	270	340	205	275	345	205	275	345	
	(OLS = V_{CC} - 0.4 V) DIV/2	215	285	355	220	290	360	220	290	360	
	(OLS = V_{CC} - 0.4 V) DFF	195	260	325	200	265	330	200	265	330	
	(OLS = V_{CC} -0.8 V, OLS = FLOAT) DIV/2	220	290	360	220	295	370	220	295	370	
	(OLS = V_{CC} - 0.8 V, OLS = FLOAT) DFF	200	265	330	200	270	340	200	270	340	
	**(OLS = V_{EE}) DIV/2	215	285	355	220	290	360	220	290	360	
	**(OLS = V_{EE}) DFF	195	260	325	200	265	330	200	265	330	
t_{SKEW}	Duty Cycle Skew (Notes 28 and 30) DFF		5	20		5	20		5	20	ps
t_{JITTER}	RMS Random Clock Jitter $f_{in} \leq$ 8 GHz		0.5	1.5		0.5	1.5		0.5	1.5	ps
	(See Figures 4 and 6) (Note 27) Peak-to-Peak Data Dependent Jitter f_{in} = 8 Gb/s					TBD					
V_{INPP}	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 29)	75		2600	75		2600	75		2600	mV
t_r t_f	Output Rise/Fall Times (20% - 80%) @ 1 GHz										ps
	Q, $\overline{Q}$										
	(OLS = V_{CC})	30	50	65	30	50	65	30	50	65	
	(OLS = V_{CC} - 0.4 V)	20	40	60	20	40	60	20	40	60	
	(OLS = V_{CC} - 0.8 V, OLS = FLOAT)	25	45	65	25	45	65	25	45	65	
	**(OLS = V_{EE})	25	45	65	25	45	65	25	45	65	
t_s	Setup Time D→CLK	30	14		30	10		30	13		ps
t_h	Hold Time D→CLK	25	12		25	7		25	9		ps
t_{rr}	Reset Recovery DFF, DIV/2	40	9		40	12		40	10		ps

27. Measured using a 500 mV source, 50% duty cycle clock source. Repetitive 1010 input data pattern. All outputs loaded with 50 Ω to V_{CC} - 2.0 V. Input edge rates is 40 ps (20% - 80%).
28. See Figure 14. $t_{SKEW} = |t_{PLH} - t_{PHL}|$ for a nominal 50% differential clock input waveform.
29. V_{INPP} (MAX) cannot exceed $V_{CC} - V_{EE}$ (Applicable only when $V_{CC} - V_{EE} < 2600$ mV).
30. See Figure 10. Duty Cycle % vs. Frequency.

**When an output level of 400 mV is desired and $V_{CC} - V_{EE} > 3.0$ V, a 2 kΩ resistor should be connected from OLS to V_{EE}.

Table 11. AC CHARACTERISTICS for QFN-16

V_{CC} = 0 V; V_{EE} = -3.465 V to -2.375 V or V_{CC} = 2.375 V to 3.465 V; V_{EE} = 0 V

		-40 °C			25°C			85°C			
Symbol	**Characteristic**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
f_{max}	Maximum Frequency (See Figures 4, 6, 8, 10, and 11) DFF (See Figures 5, 7, 9, 10, and 11) (Note 31) DIV/2		8 10			8 10			8 10		GHz
t_{PLH}, t_{PHL}	Propagation Delay to Output Differential (Note 35) CLK→Q, $\overline{Q}$ SEL→Q, $\overline{Q}$ R→Q, $\overline{Q}$ D_{IN}/2 DFF	 150 160 215 195	 215 190 280 270	 285 280 375 345	 150 160 215 195	 215 190 280 270	 285 280 375 345	 150 160 215 195	 215 190 280 270	 285 280 375 345	ps
t_{SKEW}	Duty Cycle Skew (Notes 32 and 34) DFF		5	20		5	20		5	20	ps
t_{JITTER}	RMS Random Clock Jitter $f_{in} \leq$ 8 GHz (See Figures 4 and 6) (Note 31) Peak-to-Peak Data Dependent Jitter f_{in} = 8 Gb/s		0.5 TBD	1		0.5 TBD	1		0.5 TBD	1	ps
V_{INPP}	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 33)	75		2600	75		2600	75		2600	mV
t_r t_f	Output Rise/Fall Times (20% - 80%) @ 1 GHz Q, $\overline{Q}$ (OLS = V_{CC}) (OLS = V_{CC} - 0.4 V) (OLS = V_{CC} - 0.8 V, OLS = FLOAT) **(OLS = V_{EE})	 28 15 25 20	 40 40 35 35	 65 65 65 65	 28 15 25 20	 40 40 35 35	 65 65 65 65	 28 15 25 20	 40 40 35 35	 65 65 65 65	ps
t_s	Setup Time D→CLK	30	14		30	10		30	13		ps
t_h	Hold Time D→CLK	25	12		25	7		25	0		ps
t_{rr}	Reset Recovery DFF, DIV/2	40	9		40	12		40	10		ps

31. Measured using a 500 mV source, 50% duty cycle clock source. Repetitive 1010 input data pattern. All outputs loaded with 50 Ω to V_{CC} - 2.0 V. Input edge rates is 40 ps (20% - 80%).
32. See Figure 14. $t_{SKEW} = |t_{PLH} - t_{PHL}|$ for a nominal 50% differential clock input waveform.
33. V_{INPP} (MAX) cannot exceed V_{CC} - V_{EE} (Applicable only when V_{CC} - V_{EE} < 2600 mV).
34. See Figure 10. Duty Cycle % vs. Frequency.
35. For all OLS Configuration.

**When an output level of 400 mV is desired and V_{CC} - V_{EE} > 3.0 V, a 2 kΩ resistor should be connected from OLS to V_{EE}.

***The device packaged in FCBGA-16 have maximum ambient temperature specification of 70°C and devices packaged in QFN-16 have maximum ambient temperature specification of 85°C.

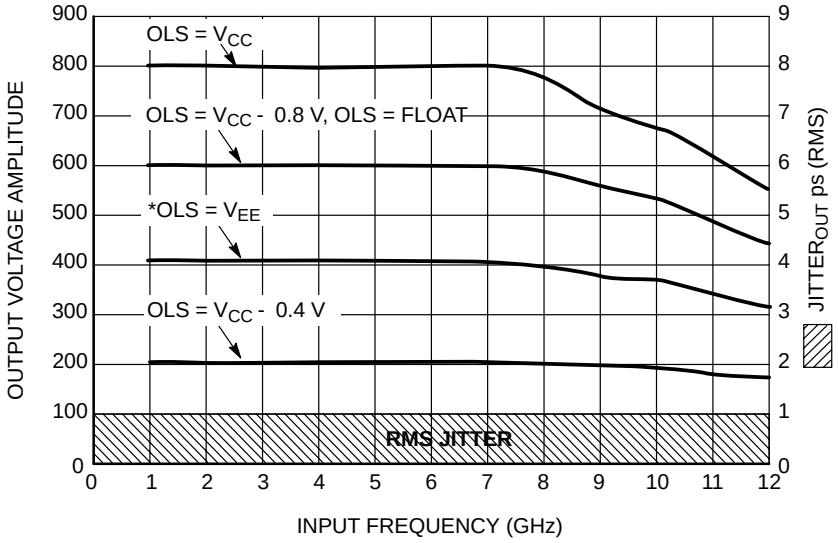


Figure 4. Output Voltage Amplitude (V_{OUTPP}) / RMS Jitter vs. Input Frequency (f_{in}) for DFF Mode (V_{CC} - V_{EE} = 3.3 V @ 25°C; Repetitive 1010 Input Data Pattern)

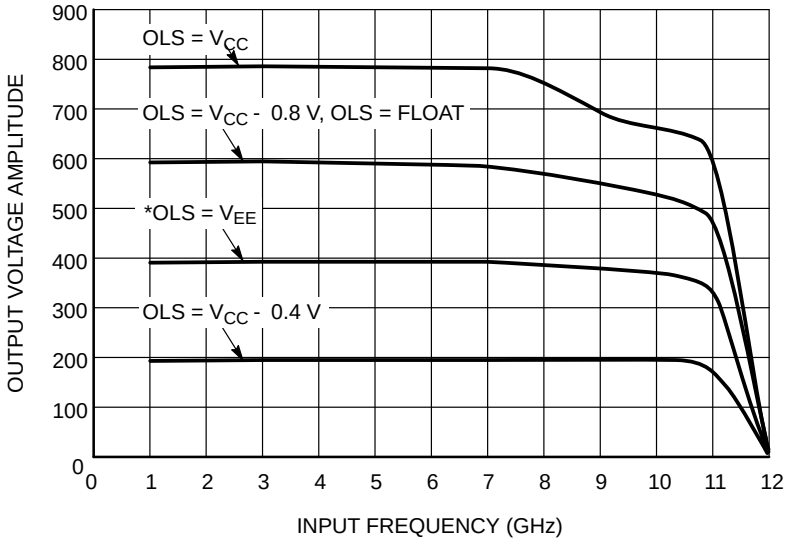


Figure 5. Output Voltage Amplitude (V_{OUTPP}) / RMS Jitter vs. Input Frequency (f_{in}) for DIV/2 Mode (V_{CC} - V_{EE} = 3.3 V @ 25°C)

*When an output level of 400 mV is desired and V_{CC} - V_{EE} > 3.0 V, a 2 kΩ resistor should be connected from OLS to V_{EE}.

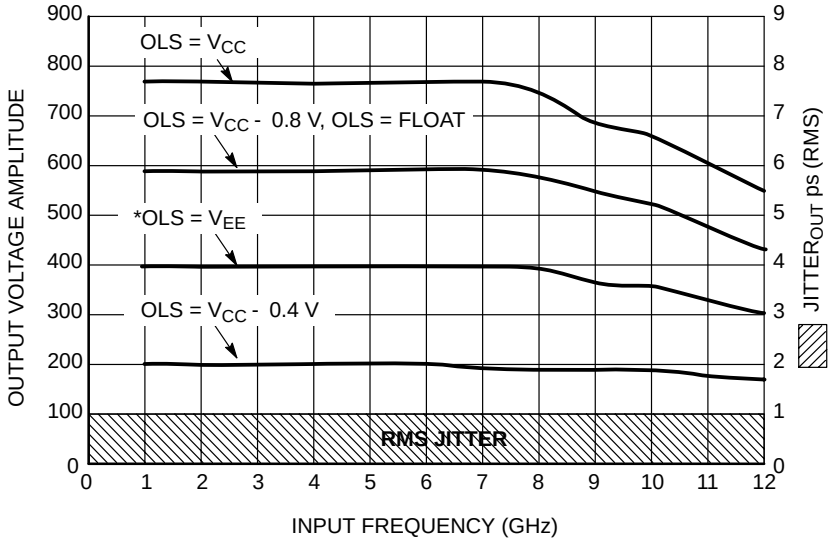


Figure 6. Output Voltage Amplitude (V_{OUTPP}) / RMS Jitter vs. Input Frequency (f_{in}) for DFF Mode (V_{CC} - V_{EE} = 2.5 V @ 25°C; Repetitive 1010 Input Data Pattern)

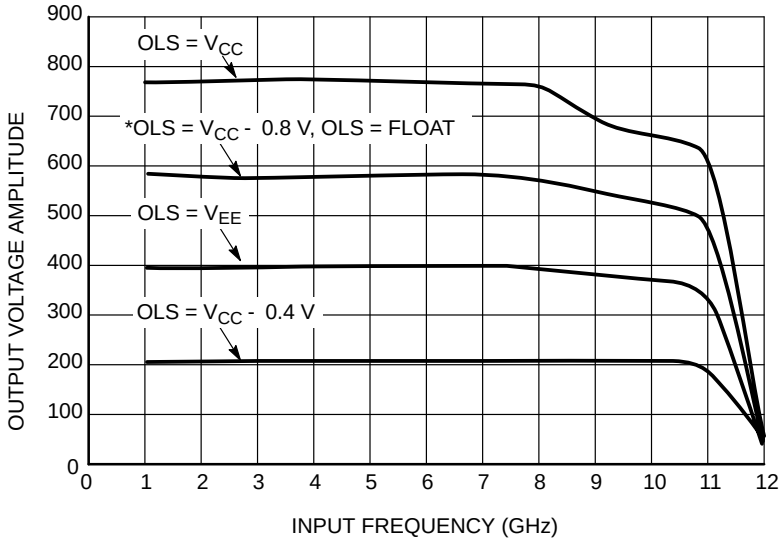


Figure 7. Output Voltage Amplitude (V_{OUTPP}) / RMS Jitter vs. Input Frequency (f_{in}) for DIV/2 Mode (V_{CC} - V_{EE} = 2.5 V @ 25°C)

*When an output level of 400 mV is desired and V_{CC} - V_{EE} > 3.0 V, a 2 kΩ resistor should be connected from OLS to V_{EE}.

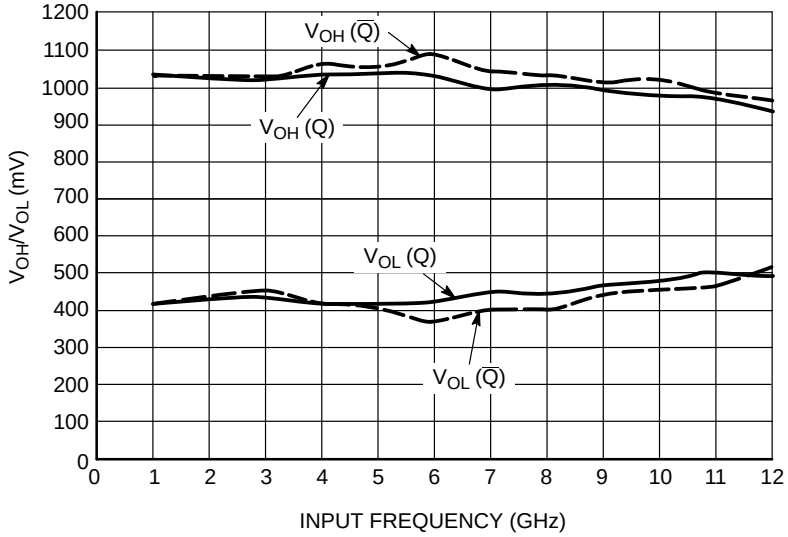


Figure 8. V_{OH}/V_{OL} ($Q/\overline{Q}$) vs. Input Frequency (f_{in}) for DFF Mode (V_{CC} - V_{EE} = 3.3 V @ 25°C and OLS = V_{CC} - 0.8 V, OLS = FLOAT)

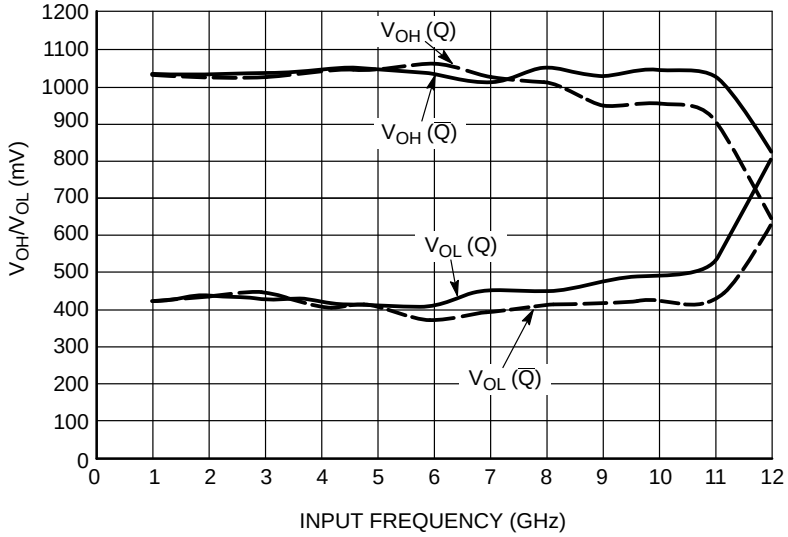


Figure 9. V_{OH}/V_{OL} ($Q/\overline{Q}$) vs. Input Frequency (f_{in}) for DIV/2 Mode (V_{CC} - V_{EE} = 3.3 V @ 25°C and OLS = V_{CC} - 0.8 V, OLS = FLOAT)

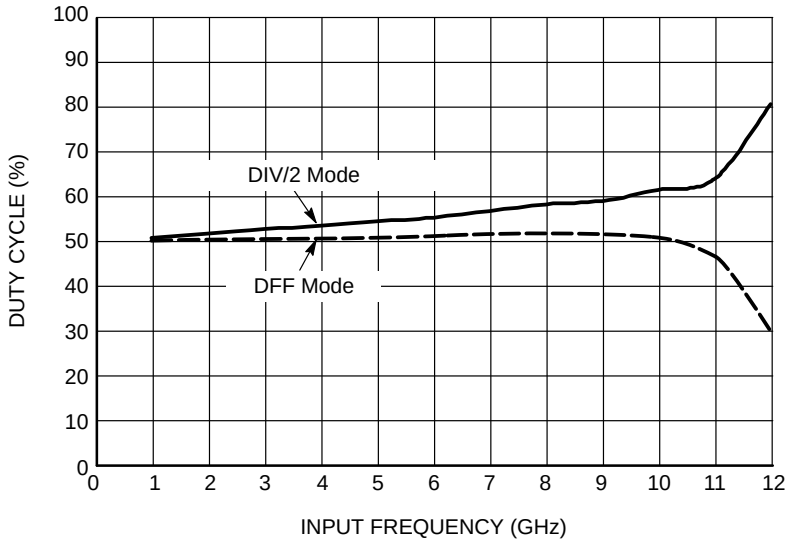


Figure 10. Duty Cycle % vs. Input Frequency (f_{in}) (V_{CC} - V_{EE} = 3.3 V @ 25°C)

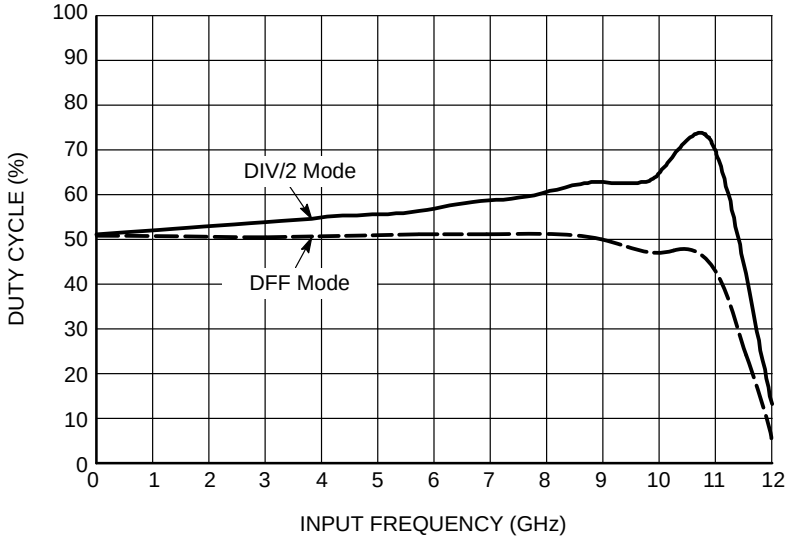


Figure 11. Duty Cycle % vs. Input Frequency (f_{in}) (V_{CC} - V_{EE} = 2.5 V @ 70°C)

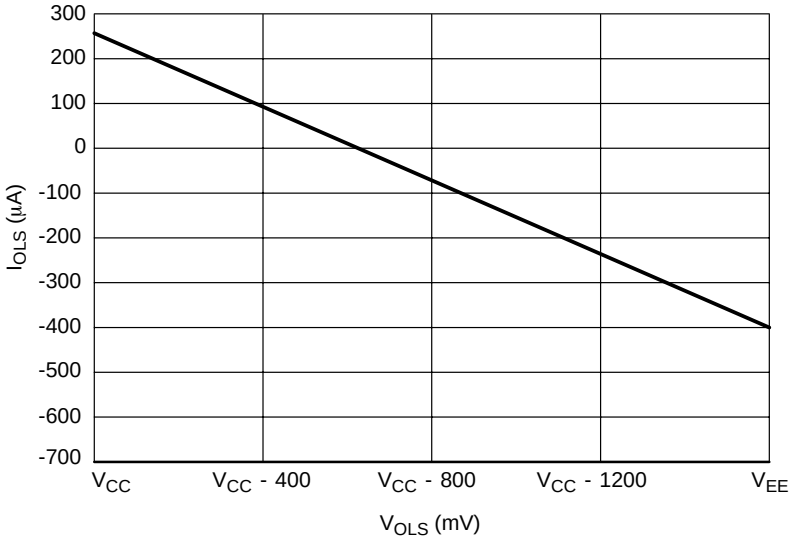


Figure 12. Typical OLS Input Current vs. OLS Input Voltage (V_{CC} - V_{EE} = 3.3 V @ 25°C)

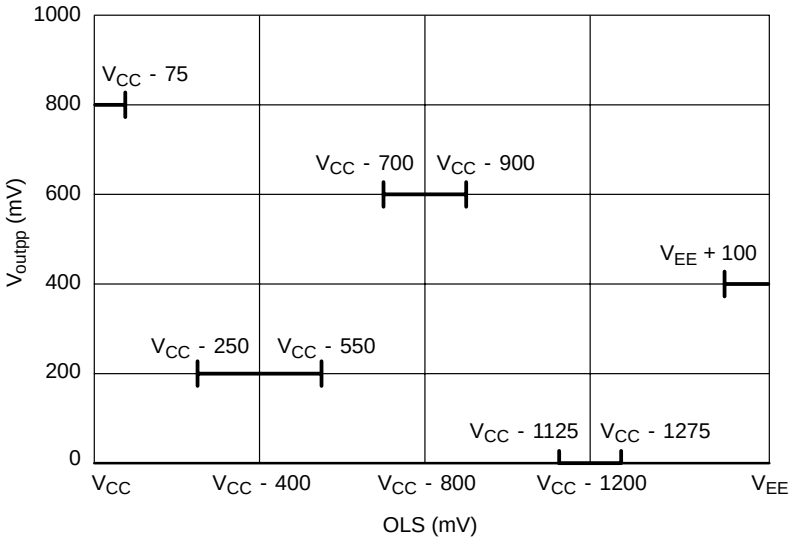


Figure 13. OLS Operating Area

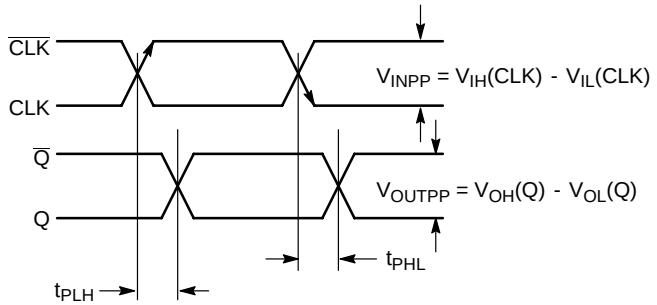


Figure 14. AC Reference Measurement

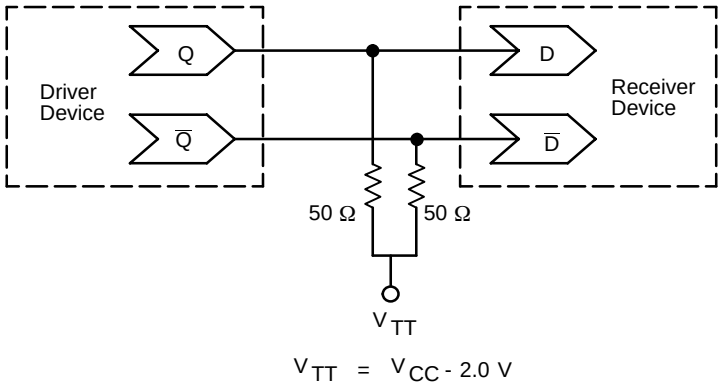
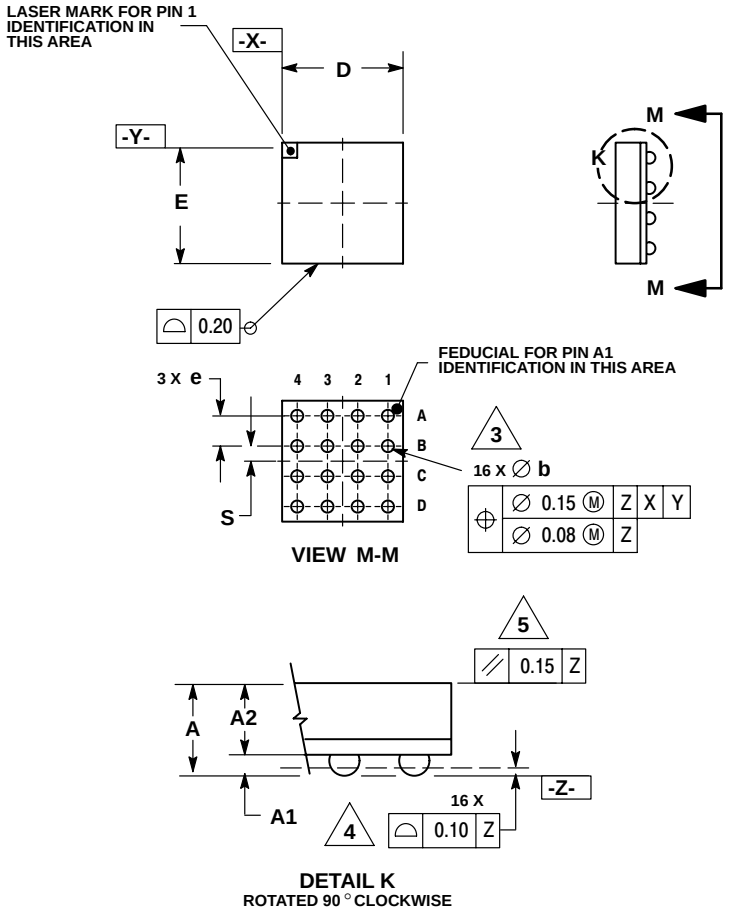


Figure 15. Typical Termination for Output Driver and Device Evaluation (Refer to Application Note AND8020 - Termination of ECL Logic Devices)

PACKAGE DIMENSIONS

FCBGA-16
BA SUFFIX
PLASTIC 4 X 4 (mm) BGA FLIP CHIP PACKAGE
CASE 489-01
ISSUE O

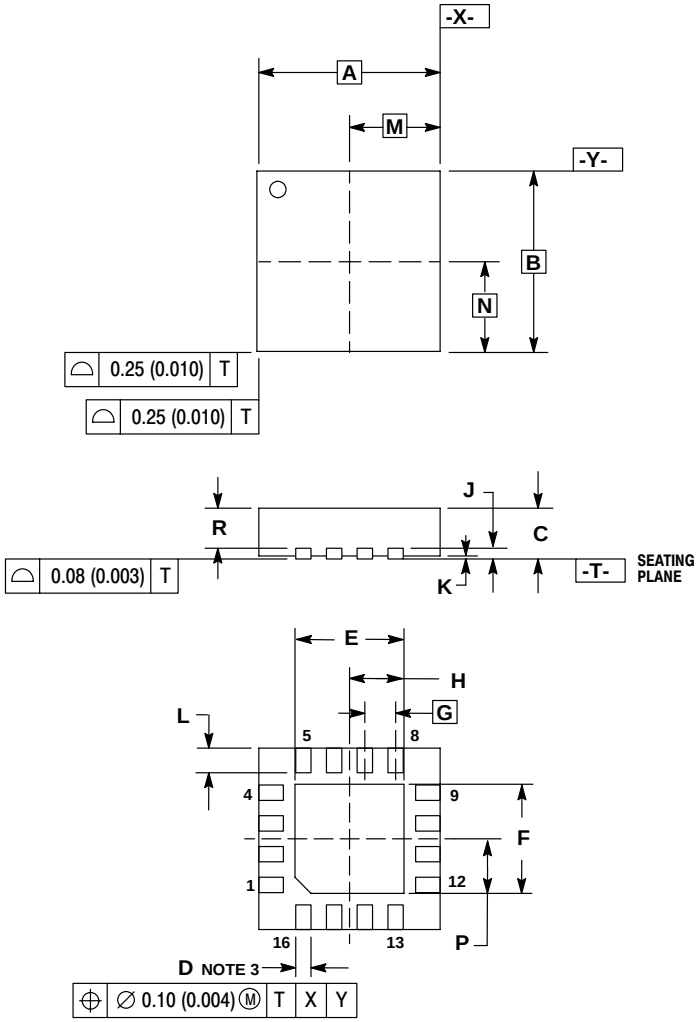


NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE Z.
4. DATUM Z (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

	MILLIMETERS	
DIM	MIN	MAX
A	1.40 MAX	
A1	0.25	0.35
A2	1.20 REF	
b	0.30	0.50
D	4.00 BSC	
E	4.00 BSC	
e	1.00 BSC	
S	0.50 BSC	

PACKAGE DIMENSIONS

16 PIN QFN
MN SUFFIX
CASE 485G-01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION D APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	3.00 BSC		0.118 BSC	
B	3.00 BSC		0.118 BSC	
C	0.80	1.00	0.031	0.039
D	0.23	0.28	0.009	0.011
E	1.75	1.85	0.069	0.073
F	1.75	1.85	0.069	0.073
G	0.50 BSC		0.020 BSC	
H	0.875	0.925	0.034	0.036
J	0.20 REF		0.008 REF	
K	0.00	0.05	0.000	0.002
L	0.35	0.45	0.014	0.018
M	1.50 BSC		0.059 BSC	
N	1.50 BSC		0.059 BSC	
P	0.875	0.925	0.034	0.036
R	0.60	0.80	0.024	0.031

GigaComm is a trademark of Semiconductor Components Industries, LLC (SCILLC).

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

JAPAN: ON Semiconductor, Japan Customer Focus Center
2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051
Phone: 81-3-5773-3850

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local Sales Representative.